

**PRODUCT / PROCESS CHANGE INFORMATION**

**1. PCI basic data**

|                      |                                                                                                  |                                      |
|----------------------|--------------------------------------------------------------------------------------------------|--------------------------------------|
| 1.1 Company          |                 | STMicroelectronics International N.V |
| 1.2 PCI No.          | EMBEDDED PROCESSING/26/16284                                                                     |                                      |
| 1.3 Title of PCI     | JSCC (China) – Leadframe redesign for molding machine compatibility on the VQFPN 8x8 68L package |                                      |
| 1.4 Product Category | STM32H56x, STM32H57x, STM32H72x, STM32H73x, STM32H7Rx, STM32H7Sx, STM32WB55x and STM32WBA6x      |                                      |
| 1.5 Issue date       | 2026-09-01                                                                                       |                                      |

**2. PCI Team**

|                                  |                          |
|----------------------------------|--------------------------|
| <b>2.1 Contact supplier</b>      |                          |
| 2.1.1 Name                       | ROBERTSON HEATHER        |
| 2.1.2 Phone                      | +1 8475853058            |
| 2.1.3 Email                      | heather.robertson@st.com |
| <b>2.2 Change responsibility</b> |                          |
| 2.2.1 Product Manager            | Patrick AIDOUNE          |
| 2.1.2 Marketing Manager          | Marie TOURNUT            |
| 2.1.3 Quality Manager            | Pascal NARCHE            |

**3. Change**

|              |                                                              |                            |
|--------------|--------------------------------------------------------------|----------------------------|
| 3.1 Category | 3.2 Type of change                                           | 3.3 Manufacturing Location |
| Materials    | Direct Material: Leadframe - Any Other change: design, etc.) | JSCC (China)               |

**4. Description of change**

|                                                                                       |                                                                                |                                                                                                                 |
|---------------------------------------------------------------------------------------|--------------------------------------------------------------------------------|-----------------------------------------------------------------------------------------------------------------|
|                                                                                       | Old                                                                            | New                                                                                                             |
| 4.1 Description                                                                       | Current Mold Machine: ASM,<br>Current Leadframe design is only for ASM machine | New Mold Machine: TOWA<br>New Strip outline of Lead frame was redesigned to meet layout of new molding machine. |
| 4.2 Anticipated Impact on form,fit, function, quality, reliability or processability? | no impact on final product                                                     |                                                                                                                 |

**5. Reason / motivation for change**

|                      |                                                                                                                                                                                                                                               |
|----------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 5.1 Motivation       | ST VQFN8X8 demand is increase and JSCC will phase out old ASM machine, so to qualify TOWA machine for capacity increase. Due to different mold machine model, Strip outline of Lead frame need redesign to meet new layout of molding machine |
| 5.2 Customer Benefit | SERVICE IMPROVEMENT                                                                                                                                                                                                                           |

**6. Marking of parts / traceability of change**

|                 |                                            |
|-----------------|--------------------------------------------|
| 6.1 Description | traceability ensured by ST internal tools. |
|-----------------|--------------------------------------------|

**7. Timing / schedule**

|                                     |                |
|-------------------------------------|----------------|
| 7.1 Date of qualification results   | 2026-08-10     |
| 7.2 Intended start of delivery      | 2026-10-05     |
| 7.3 Qualification sample available? | Not Applicable |

**8. Qualification / Validation**

|                                                    |                                                                                              |            |            |
|----------------------------------------------------|----------------------------------------------------------------------------------------------|------------|------------|
| 8.1 Description                                    | 16284 MDG-MCD RERMCD1524 - STM32F7x- Die 452XXA - Reliability Evaluation Report - REV1.3.pdf |            |            |
| 8.2 Qualification report and qualification results | Available (see attachment)                                                                   | Issue Date | 2026-09-01 |

| 9. Attachments (additional documentations)                                                                                                                     |
|----------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 16284 Public product.pdf<br>16284 MDG-MCD RERMCD1524 - STM32F7x- Die 452XXxA - Reliability Evaluation Report - REV1.3.pdf<br>16284 _Additional information.pdf |

| 10. Affected parts      |                         |                          |
|-------------------------|-------------------------|--------------------------|
| 10. 1 Current           |                         | 10.2 New (if applicable) |
| 10.1.1 Customer Part No | 10.1.2 Supplier Part No | 10.1.2 Supplier Part No  |
|                         | STM32H562RGV6           |                          |
|                         | STM32H562RIV6           |                          |
|                         | STM32H563RGV6           |                          |
|                         | STM32H563RIV6           |                          |
|                         | STM32H573RIV6           |                          |
|                         | STM32H725RGV3           |                          |
|                         | STM32H725RGV6           |                          |
|                         | STM32H735RGV6           |                          |
|                         | STM32H7R3R8V6           |                          |
|                         | STM32H7S3R8V6           |                          |
|                         | STM32WB55RCV6           |                          |
|                         | STM32WB55RCV7           |                          |
|                         | STM32WB55REV6           |                          |
|                         | STM32WB55REV7           |                          |
|                         | STM32WB55RGV6           |                          |
|                         | STM32WB55RGV6TR         |                          |
|                         | STM32WB55RGV7           |                          |
|                         | STM32WBA65RIV6          |                          |

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